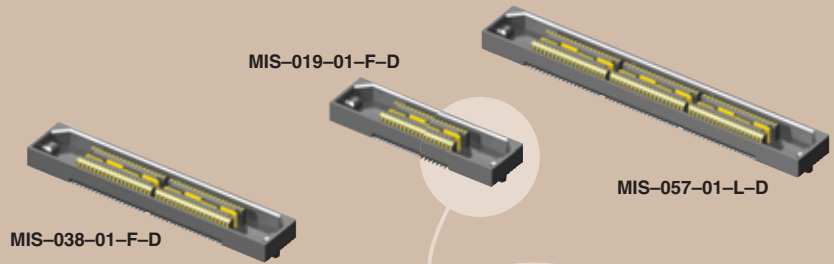




(0,635mm) .025"

MIS SERIES



THROUGH-HOLE GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over 50µ" (1,27µm) Ni
Current Rating:
Contacts: 1.6A @ 80°C
Ground Plane: 8.7A @ 80°C
Operating Temp Range:
-55°C to +125°C
Voltage Rating:
275 VAC
Max Cycles:
100
RoHS Compliant:
Yes

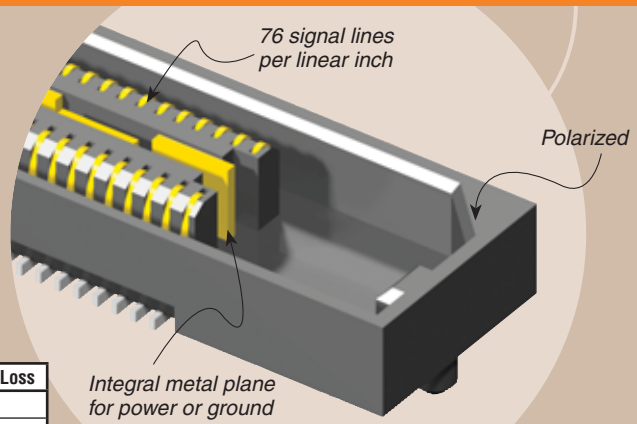


Board Mates:
MIT

Cable Mates:
MICD

5mm Stack Height	Type	Rated @ -3dB Insertion Loss
Single-Ended Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com?MIS or contact sig@samtec.com



Processing:

Max Processing Temp:
230°C for 60 seconds, or
260°C for 20 seconds 3x
Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0,10mm) .004" max (019-076)
Board Stacking:
For applications requiring more than two connectors per board or 76 positions or higher, contact ipg@samtec.com

ALSO AVAILABLE

Board Spacing Standoffs.
See SO Series.

APPLICATION SPECIFIC OPTION

- 11mm, 16mm, 18,75mm and 22mm stack height
 - 30µ" (0,76µm) Gold
 - Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
 - 95, 114 and 133 positions per row
 - Edge Mount
- Call Samtec.



-019, -038, -057, -076
(38 total positions per bank)

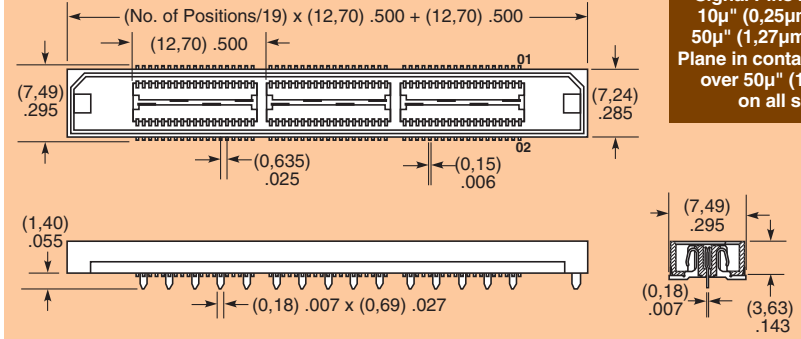
-F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

-L
= 10µ" (0,25µm)
Gold on Signal Pins and Ground Plane, Matte Tin on tails

-C*
= Electro-Polished Selective
50µ" (1,27µm) min Au over
150µ" (3,81µm) Ni on
Signal Pins in contact area,
10µ" (0,25µm) min Au over
50µ" (1,27µm) Ni on Ground
Plane in contact area, Matte Tin
over 50µ" (1,27µm) min Ni
on all solder tails

-K
= (7,00mm) .275" DIA
Polyimide film Pick & Place Pad

-TR
= Tape & Reel



Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

***Note:** -C Plating passes 10 year MFG testing
Note: Some lengths, styles and options are non-standard, non-returnable.